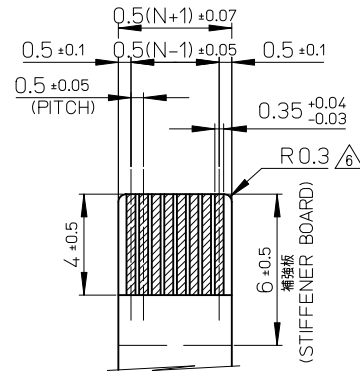


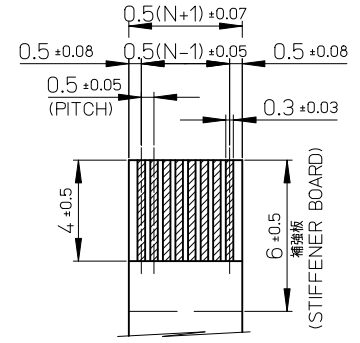
21.1	19.3	15.65	14.5	52746-3071	30
20.1	18.3	14.65	13.5	52746-2871	28
19.6	17.8	14.15	13	52746-2771	27
18.6	16.8	13.15	12	52746-2571	25
18.1	16.3	12.65	11.5	52746-2471	24
17.1	15.3	11.65	10.5	52746-2271	22
16.6	14.8	11.15	10	52746-2171	21
16.1	14.3	10.65	9.5	52746-2071	20
15.6	13.8	10.15	9	52746-1971	19
15.1	13.3	9.65	8.5	52746-1871	18
14.6	12.8	9.15	8	52746-1771	17
14.1	12.3	8.65	7.5	52746-1671	16
13.6	11.8	8.15	7	52746-1571	15
13.1	11.3	7.65	6.5	52746-1471	14
12.6	10.8	7.15	6	52746-1371	13
12.1	10.3	6.65	5.5	52746-1271	12
11.6	9.8	6.15	5	52746-1171	11
11.1	9.3	5.65	4.5	52746-1071	10
10.6	8.8	5.15	4	52746-0971	9
10.1	8.3	4.65	3.5	52746-0871	8
9.6	7.8	4.15	3	52746-0771	7
9.1	7.3	3.65	2.5	52746-0671	6
8.1	6.3	2.65	1.5	52746-0471	4
D	C	B	(A)	EMBOSSED PACKAGE ORDER No. オーダー番号	極数 CKT.

CONNECTOR SERIES NO. : 52746-**39

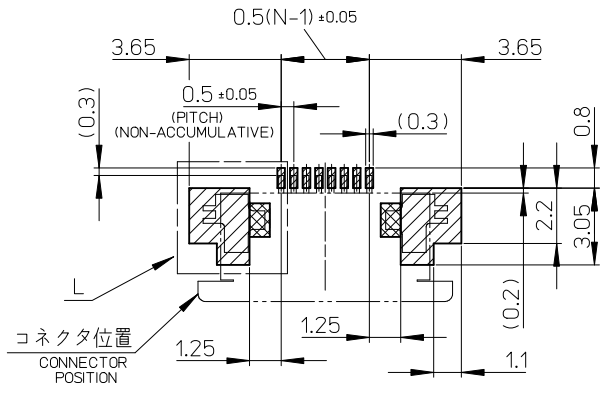
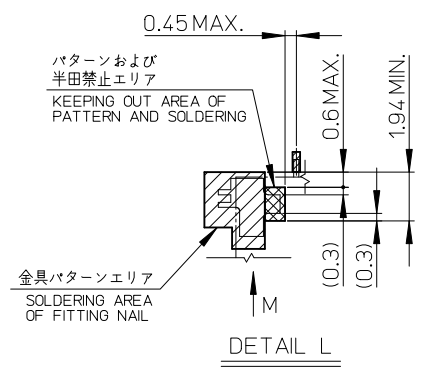
REVISED EC NO. J2011-0041 DRWN:HYOSHINO 2010/07/08 CHKD:HIJIMA 2010/07/08 APPR:KMORIKAWA 2010/07/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HSHIMABUKURO	DATE '04/01/30	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (BOTTOM CONTACT) GOLD PLATING		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE '04/01/30	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY MSASAO	DATE '04/01/30	DOCUMENT NO. SD-52746-025		
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 2	
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



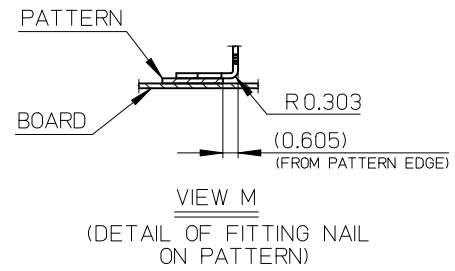
適合金めっきFPC推奨寸法
 APPLICABLE FPC OF GOLD
 PLATING RECOMMENDED DIMENSION
 仕上がり厚さ: 0.3±0.03
 THICKNESS: 0.3+0.03/-0.03



適合金めっきFPC推奨寸法
 APPLICABLE FPC OF GOLD
 PLATING RECOMMENDED DIMENSION
 仕上がり厚さ: 0.3±0.03
 THICKNESS: 0.3+0.03/-0.03



参考基板レイアウト
 (マウント面)
 RECOMMENDED P.C.BOARD
 PATTERN DIMENSION(REF.)
 (MOUNTING SIDE)



注記NOTES

- 1.使用材料
 MATERIAL
 ハウジング: 46ナイロン、ガラス充填、UL94V-0、白
 HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE
 アクチュエータ: ポリフェニレンサルファイド (PPS)、ガラス充填、UL94V-0、茶色
 ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BROWN
 ターミナル: リン青銅、ニッケル下地金めっき (t=0.2)
 TERMINAL: PHOSPHOR BRONZE, GOLD OVER NICKEL PLATING
 金具: リン青銅、ニッケル下地金めっき (t=0.2)
 FITTING NAIL: PHOSPHOR BRONZE, TIN OVER NICKEL PLATING
- 2.エンボステープ梱包時は、アクチュエータがロックした状態になります。
 IN THE PACKAGE, ACTUATOR OF PART NO.52746-***39 SHOULD BE LOCKED.
- 3.ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM DATUM-H.
 UPPER DIRECTION: 0.1MAXIMUM
 LOWER DIRECTION: 0.15 MAXIMUM
- 4.偶数極に適用
 APPLY FOR EVEN CIRCUIT.
- 5.ハ' ターン刻難止め金具
 FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.
- 6.R0.3は、FPCの導体部にかからないこと
 R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.
- 7.ELV 及び RoHS 適合品
 ELV AND RoHS COMPLIANT

FPCについて:
 打ち抜き方向は導体側から補強板を推奨いたします。
 補強フィルム材質はポリイミドを推奨いたします。
 ABOUT FPC:
 RECOMMENDED PUNCHER DIRECTION: FROM CONDUCTOR SIDE TO STIFFNER BOARD SIDE.
 RECOMMENDED MATERIAL: POLYIMIDE
 STIFFNER FILM: POLYIMIDE
 BONDING AGENT: THERMOSETTING BONDING AGENT

REVISED EC NO: J2011-0041 DRWN:HYOSHINO 2010/07/08 CHKD:HIJIMA 2010/07/08 APPR:KMORIKAWA 2010/07/16	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY HSHIMABUKURO	DATE '04/01/30	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (BOTTOM CONTACT) GOLD PLATING			
		10 OVER 30 UNDER	± ---	CHECKED BY KTOJO	DATE '04/01/30	MOLEX INCORPORATED			
		30 OVER	± ---	APPROVED BY MSASAO	DATE '04/01/30	DOCUMENT NO. SD-52746-025			
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SHEET NO. 2 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	